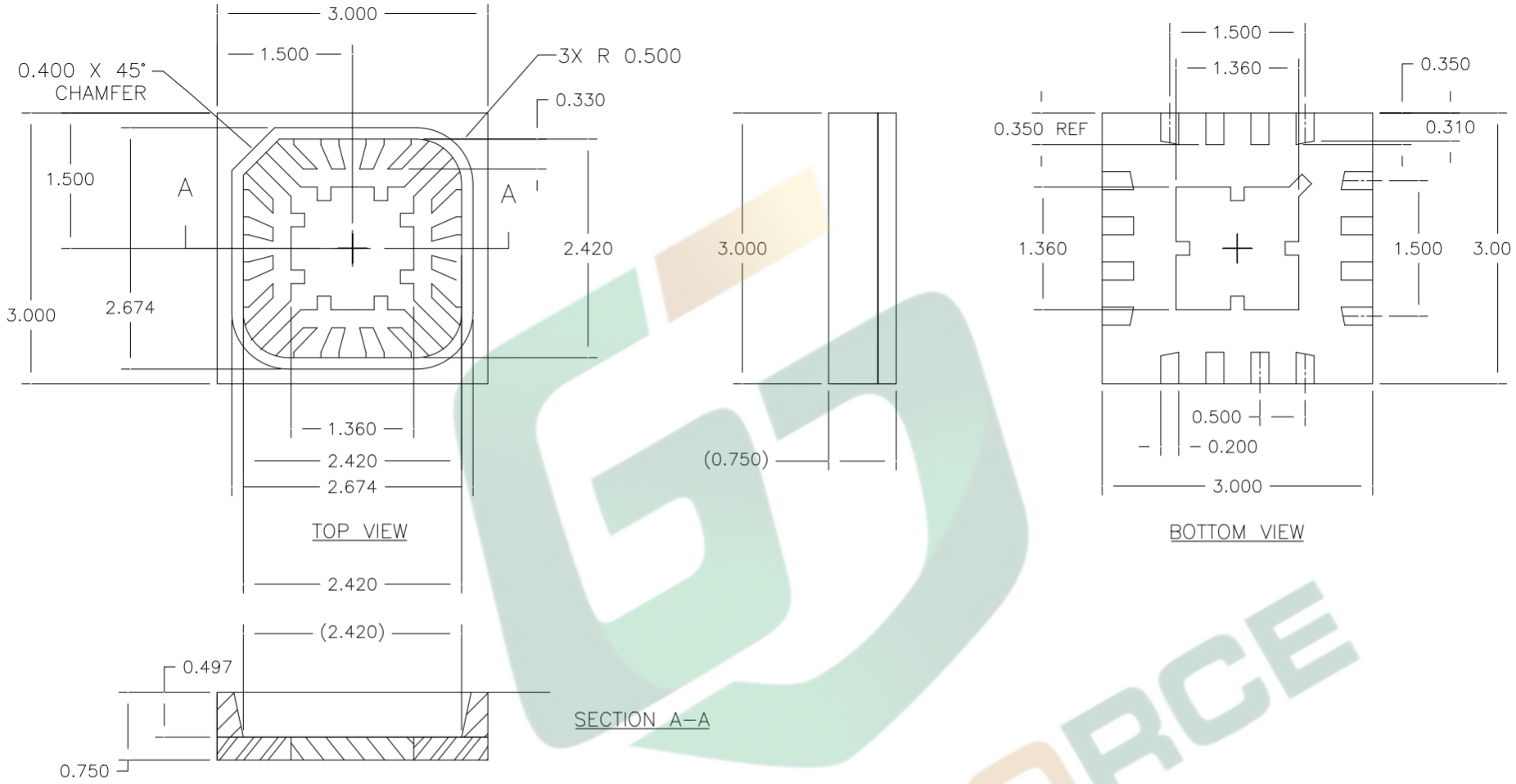

N TES:

1. BODY: PLASTIC, SEMICONDUCTOR GRADE.
3. LEAD FRAME: COPPER, 194 FH.
4. LEAD FINISH: FULL GOLD PLATE.
5. FRAME THICKNESS: 0.2030 ±.0076.
6. DIE PAD: 1.360mm X 1.360mm.
7. JEDEC UTLINE: MO-220 (VEED)

GIGA FORCE	上海季丰电子科技有限公司 GIGA FORCE ELECTRONICS CO.,Limited				
制图	胡熠文	Title	QFN16L(3X3)-P0.5		
核准	何桂港	POD No	POD-SHJF-52		
日期	2023.1.31	DIMENSIONS IN:	mm	Rev:A	